## 100 V, 2.0 A, Low V<sub>CE(sat)</sub> PNP Transistor

ON Semiconductor's  $e^2$ PowerEdge family of low  $V_{CE(sat)}$ transistors are miniature surface mount devices featuring ultra low saturation voltage ( $V_{CE(sat)}$ ) and high current gain capability. These are designed for use in low voltage, high speed switching applications where affordable efficient energy control is important.

Typical applications are DC–DC converters and power management in portable and battery powered products such as cellular and cordless phones, PDAs, computers, printers, digital cameras and MP3 players. Other applications are low voltage motor controls in mass storage products such as disc drives and tape drives. In the automotive industry they can be used in air bag deployment and in the instrument cluster. The high current gain allows e<sup>2</sup>PowerEdge devices to be driven directly from PMU's control outputs, and the Linear Gain (Beta) makes them ideal components in analog amplifiers.

#### Features

- NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

<b>MAXIMUM RATINGS</b> ( $T_A = 25^{\circ}C$ )					
Rating	Symbol	Max	Unit		
Collector-Emitter Voltage	V <sub>CEO</sub>	-100	Vdc		
Collector-Base Voltage	V <sub>CBO</sub>	-140	Vdc		
Emitter-Base Voltage	V <sub>EBO</sub>	-7.0	Vdc		
Collector Current – Continuous	۱ <sub>C</sub>	-2.0	Α		
Collector Current – Peak	I <sub>CM</sub>	-3.0	Α		

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub> (Note 1)	490 3.7	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$ (Note 1)	255	°C/W
Total Device Dissipation T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub> (Note 2)	710 4.3	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$ (Note 2)	176	°C/W
Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	–55 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. FR-4 @ 100 mm<sup>2</sup>, 1 oz. copper traces.

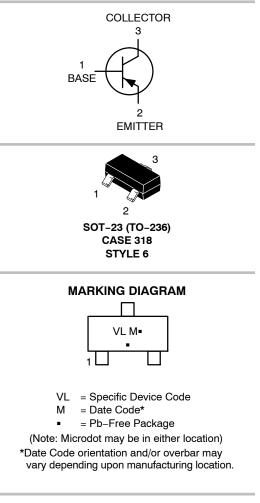
2. FR-4 @ 500 mm<sup>2</sup>, 1 oz. copper traces.



#### **ON Semiconductor®**

www.onsemi.com

### -100 VOLTS, 2.0 AMPS PNP LOW V<sub>CE(sat)</sub> TRANSISTOR



#### ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
NSS1C200LT1G, NSV1C200LT1G	SOT-23 (Pb-Free)	3000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

#### **ELECTRICAL CHARACTERISTICS** ( $T_A = 25^{\circ}C$ unless otherwise noted)

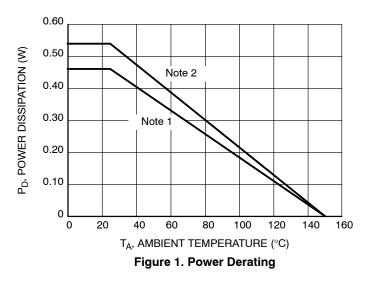
Characteristic	Symbol	Min	Тур	Max	Unit	
OFF CHARACTERISTICS						
Collector – Emitter Breakdown Voltage ( $I_C = -10 \text{ mAdc}, I_B = 0$ )	V <sub>(BR)CEO</sub>	-100			Vdc	
Collector – Base Breakdown Voltage (I <sub>C</sub> = -0.1 mAdc, I <sub>E</sub> = 0)	V <sub>(BR)CBO</sub>	-140			Vdc	
Emitter – Base Breakdown Voltage (I <sub>E</sub> = -0.1 mAdc, I <sub>C</sub> = 0)	V <sub>(BR)EBO</sub>	-7.0			Vdc	
Collector Cutoff Current (V <sub>CB</sub> = -140 Vdc, I <sub>E</sub> = 0)	I <sub>CBO</sub>			-100	nAdc	
Emitter Cutoff Current (V <sub>EB</sub> = -6.0 Vdc)	I <sub>EBO</sub>			-50	nAdc	

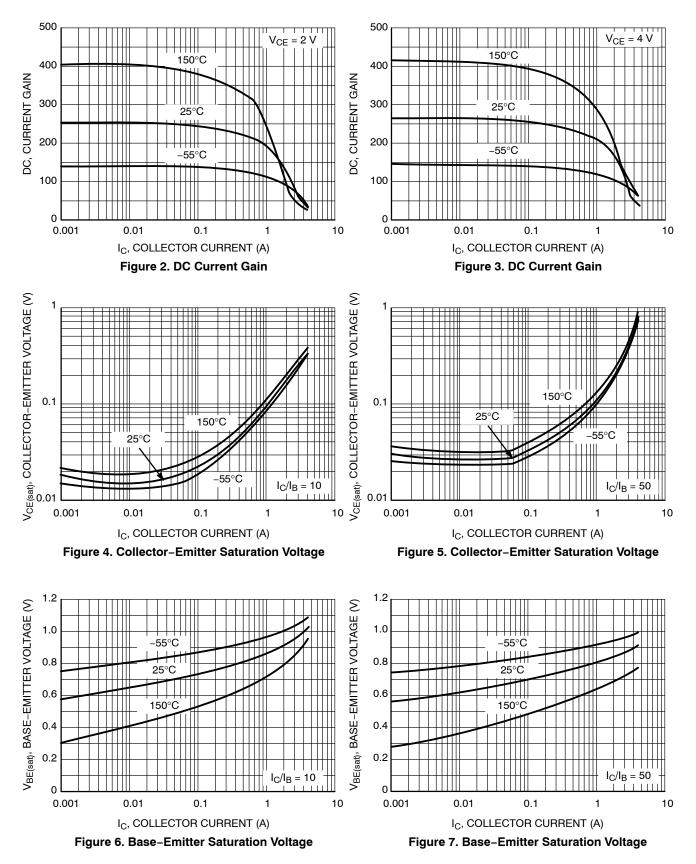
#### ON CHARACTERISTICS

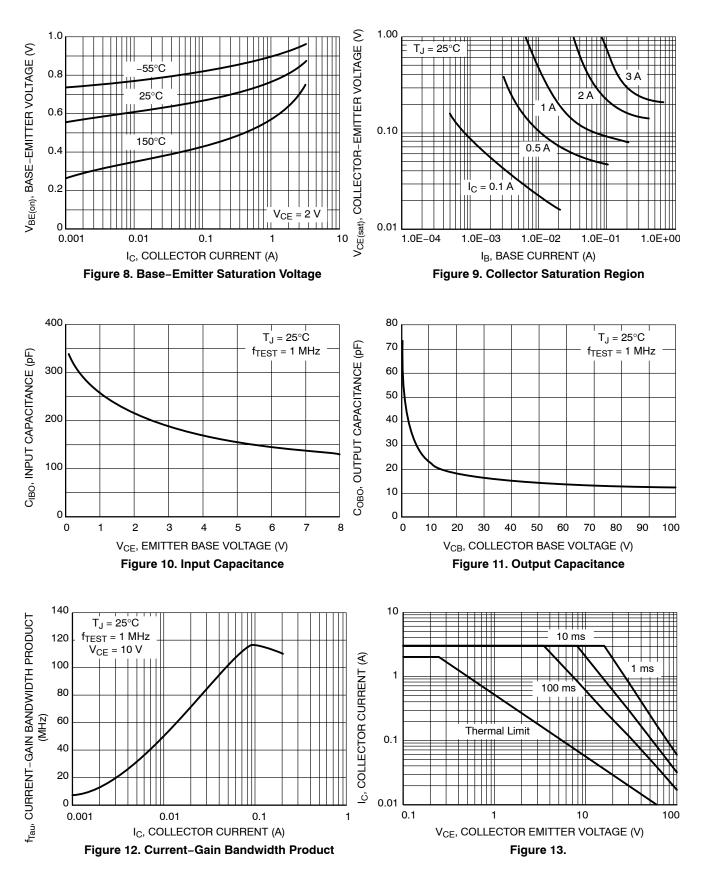
$ \begin{array}{l} \mbox{DC Current Gain (Note 3)} \\ (I_{C} = -10 \mbox{ mA}, \mbox{V}_{CE} = -2.0 \mbox{ V}) \\ (I_{C} = -500 \mbox{ mA}, \mbox{V}_{CE} = -2.0 \mbox{ V}) \\ (I_{C} = -1.0 \mbox{ A}, \mbox{V}_{CE} = -2.0 \mbox{ V}) \\ (I_{C} = -2.0 \mbox{ A}, \mbox{V}_{CE} = -2.0 \mbox{ V}) \end{array} $	h <sub>FE</sub>	150 120 80 50	240	360	
Collector – Emitter Saturation Voltage (Note 3) ( $I_C = -0.1 \text{ A}, I_B = -0.01 \text{ A}$ ) ( $I_C = -0.5 \text{ A}, I_B = -0.05 \text{ A}$ ) ( $I_C = -1.0 \text{ A}, I_B = -0.100 \text{ A}$ ) ( $I_C = -2.0 \text{ A}, I_B = -0.200 \text{ A}$ )	V <sub>CE(sat)</sub>			-0.040 -0.080 -0.115 -0.250	V
Base – Emitter Saturation Voltage (Note 3) ( $I_C = -1.0 \text{ A}, I_B = -0.100 \text{ A}$ )	V <sub>BE(sat)</sub>			-0.950	V
Base – Emitter Turn–on Voltage (Note 3) ( $I_C = -1.0 \text{ A}, V_{CE} = -2.0 \text{ V}$ )	V <sub>BE(on)</sub>			-0.850	V
Cutoff Frequency (I <sub>C</sub> = $-100$ mA, V <sub>CE</sub> = $-5.0$ V, f = 100 MHz)	fT		120		MHz
Input Capacitance (V <sub>EB</sub> = 2.0 V, f = 1.0 MHz)	Cibo		200		pF
Output Capacitance (V <sub>CB</sub> = 10 V, f = 1.0 MHz)	Cobo		22		pF

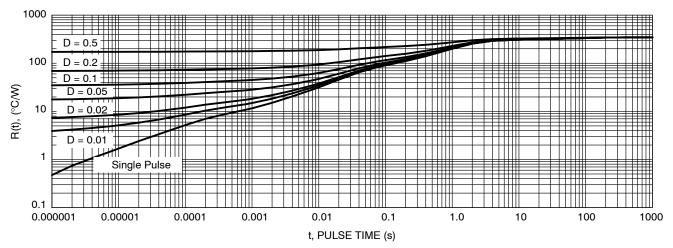
Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

3. Pulsed Condition: Pulse Width = 300 msec, Duty Cycle  $\leq$  2%.





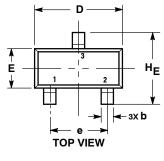


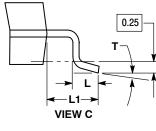


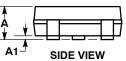


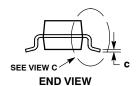
#### PACKAGE DIMENSIONS

SOT-23 (TO-236) CASE 318-08 **ISSUE AR** 









NOTES:

- 2 3
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994. CONTROLLING DIMENSION: MILLIMETERS. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH,

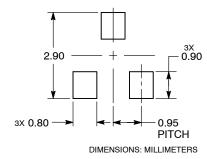
4 PROTRUSIONS, OR GATE BURRS.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.89	1.00	1.11	0.035	0.039	0.044
A1	0.01	0.06	0.10	0.000	0.002	0.004
b	0.37	0.44	0.50	0.015	0.017	0.020
с	0.08	0.14	0.20	0.003	0.006	0.008
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
е	1.78	1.90	2.04	0.070	0.075	0.080
L	0.30	0.43	0.55	0.012	0.017	0.022
L1	0.35	0.54	0.69	0.014	0.021	0.027
HE	2.10	2.40	2.64	0.083	0.094	0.104
Т	0°		10 °	0 °		10 °

STYLE 6: PIN 1. BASE

2. 3. EMITTER COLLECTOR

RECOMMENDED SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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